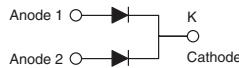
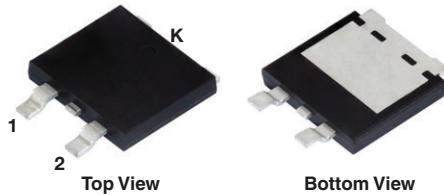


# Dual High-Voltage TMBS® (Trench MOS Barrier Schottky) Rectifier

 Ultra Low  $V_F = 0.56 \text{ V}$  at  $I_F = 2.5 \text{ A}$ 

## eSMP® Series SMPD (TO-263AC)



### DESIGN SUPPORT TOOLS AVAILABLE


[3D Models](#)

#### PRIMARY CHARACTERISTICS

|   |                 |
|---|-----------------|
| $I_{F(AV)}$   | 2 x 5 A         |
| $V_{RRM}$   | 150 V           |
| $I_{FSM}$   | 80 A            |
| $V_F$ at $I_F = 5 \text{ A}$ ( $T_J = 125 \text{ °C}$ ) | 0.63 V          |
| $T_J$ max.  | 175 °C          |
| Package   | SMPD (TO-263AC) |
| Circuit configuration                                   | Common cathode  |

### FEATURES

- Trench MOS Schottky technology
- Very low profile - typical height of 1.7 mm
- Ideal for automated placement
- Low forward voltage drop, low power losses
- High efficiency operation
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified available:
  - Automotive ordering code: base P/NHM3
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)

 AUTOMOTIVE  
GRADE  
Available

**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**

### TYPICAL APPLICATIONS

For use in high frequency DC/DC converters, switching power supplies, freewheeling diodes, OR-ing diode, and reverse battery protection in commercial, industrial, and automotive application.

### MECHANICAL DATA

**Case:** SMPD (TO-263AC)

Molding compound meets UL 94 V-0 flammability rating

Base P/N-M3 - halogen-free, RoHS-compliant

Base P/NHM3 - halogen-free, RoHS-compliant, and AEC-Q101 qualified

**Terminals:** matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

M3 and HM3 suffix meet JESD 201 class 2 whisker test

**Polarity:** as marked

#### MAXIMUM RATINGS ( $T_A = 25 \text{ °C}$ unless otherwise noted)

| PARAMETER  | SYMBOL                     | V10DM153C        | UNIT |
|--|----------------------------|------------------|------|
| Device marking code  |                            | V10DM153C        |      |
| Maximum repetitive peak reverse voltage  | $V_{RRM}$                  | 150              | V    |
| Maximum average forward rectified current  | $I_{F(AV)}$ <sup>(1)</sup> | per device<br>10 | A    |
| (fig. 1)   |                            | per diode<br>5   |      |
| Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load | $I_{FSM}$                  | 80               | A    |
| Operating junction temperature range   | $T_J$ <sup>(2)</sup>       | -40 to +175      | °C   |
| Storage temperature range  | $T_{STG}$                  | -55 to +175      |      |

#### Notes

<sup>(1)</sup> Mounted on infinite heatsink

<sup>(2)</sup> The heat generated must be less than the thermal conductivity from junction-to-ambient:  $dP_D/dT_J < 1/R_{\theta JA}$



| <b>ELECTRICAL CHARACTERISTICS</b> ( $T_J = 25\text{ }^\circ\text{C}$ unless otherwise noted) |                      |                                   |             |        |      |      |
|--|----------------------|-----------------------------------|-------------|--------|------|------|
| PARAMETER  | TEST CONDITIONS      |                                   | SYMBOL      | TYP.   | MAX. | UNIT |
| Instantaneous forward voltage per diode  | $I_F = 2.5\text{ A}$ | $T_J = 25\text{ }^\circ\text{C}$  | $V_F^{(1)}$ | 0.70   | -    | V    |
|  | $I_F = 5\text{ A}$   |                                   |             | 0.84   | 0.95 |      |
|  | $I_F = 2.5\text{ A}$ | $T_J = 125\text{ }^\circ\text{C}$ |             | 0.56   | -    |      |
|  | $I_F = 5\text{ A}$   |                                   |             | 0.63   | 0.68 |      |
| Reverse current at rated $V_R$ per diode   | $V_R = 100\text{ V}$ | $T_J = 25\text{ }^\circ\text{C}$  | $I_R^{(2)}$ | 0.0003 | -    | mA   |
|  |                      | $T_J = 125\text{ }^\circ\text{C}$ |             | 0.5    | -    |      |
|  | $V_R = 150\text{ V}$ | $T_J = 25\text{ }^\circ\text{C}$  |             | -      | 0.05 |      |
|  |                      | $T_J = 125\text{ }^\circ\text{C}$ |             | 1.25   | 4    |      |
| Typical junction capacitance   | 4.0 V, 1 MHz         |                                   | $C_J$       | 280    | -    | pF   |

**Notes**

- (1) Pulse test: 300  $\mu\text{s}$  pulse width, 1 % duty cycle  
(2) Pulse test: Pulse width  $\leq 5\text{ ms}$

| <b>THERMAL CHARACTERISTICS</b> ( $T_A = 25\text{ }^\circ\text{C}$ unless otherwise noted) |                          |           |                    |
|---|--------------------------|-----------|--------------------|
| PARAMETER   | SYMBOL                   | V10DM153C | UNIT               |
| Typical thermal resistance per device   | $R_{\theta JC}^{(1)}$    | 2.7       | $^\circ\text{C/W}$ |
|   | $R_{\theta JA}^{(2)(3)}$ | 58        |                    |

**Notes**

- (1) Mounted on infinite heatsink  
(2) The heat generated must be less than the thermal conductivity from junction-to-ambient:  $dP_D/dT_J < 1/R_{\theta JA}$  - junction-to-ambient  
(3) Free air, without heatsink

| <b>ORDERING INFORMATION</b> (Example) |                 |              |               |                                    |
|---------------------------------------|-----------------|--------------|---------------|------------------------------------|
| PREFERRED P/N                         | UNIT WEIGHT (g) | PACKAGE CODE | BASE QUANTITY | DELIVERY MODE                      |
| V10DM153C-M3/I                        | 0.55            | I            | 2000/reel     | 13" diameter plastic tape and reel |
| V10DM153CHM3/I <sup>(1)</sup>         | 0.55            | I            | 2000/reel     | 13" diameter plastic tape and reel |

**Note**

- (1) AEC-Q101 qualified

**RATINGS AND CHARACTERISTICS CURVES** ( $T_A = 25\text{ }^\circ\text{C}$  unless otherwise noted)

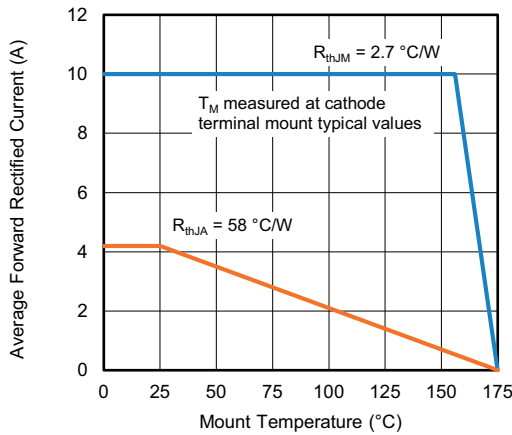


Fig. 1 - Maximum Forward Current Derating Curve

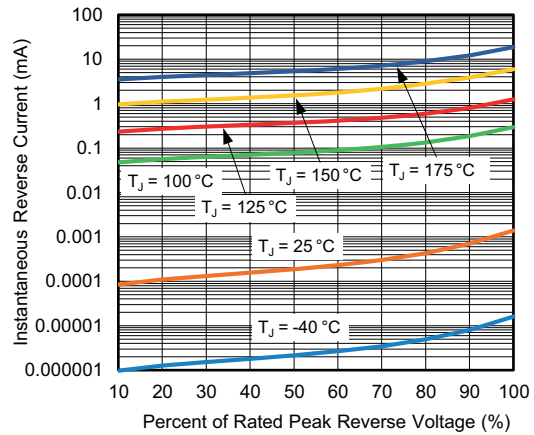


Fig. 4 - Typical Reverse Leakage Characteristics

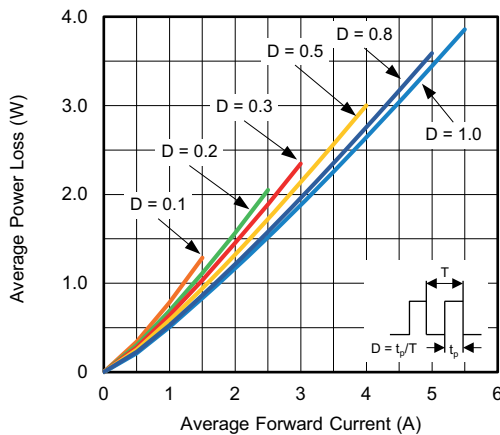


Fig. 2 - Average Power Loss Characteristics

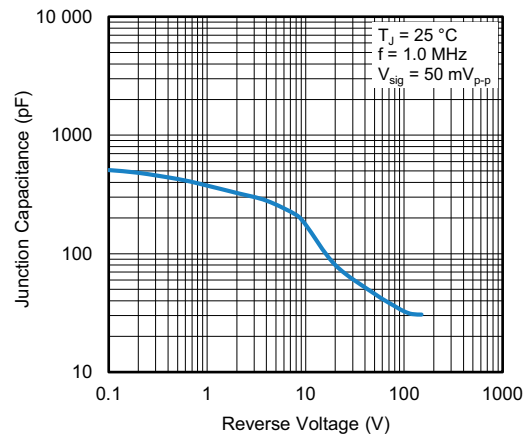


Fig. 5 - Typical Junction Capacitance

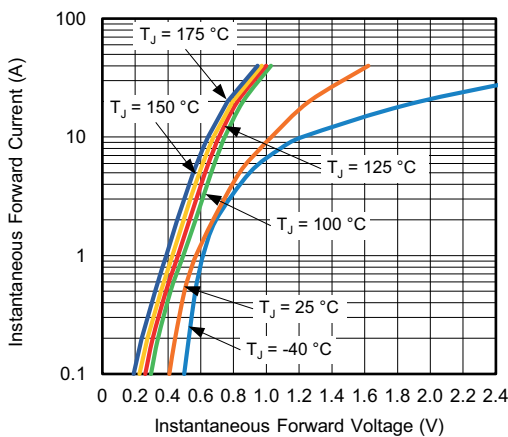


Fig. 3 - Typical Instantaneous Forward Characteristics

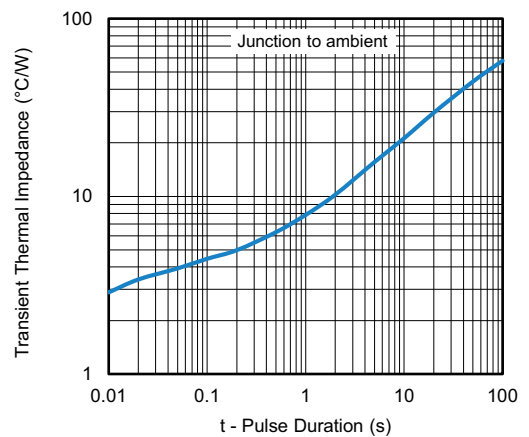


Fig. 6 - Typical Transient Thermal Impedance

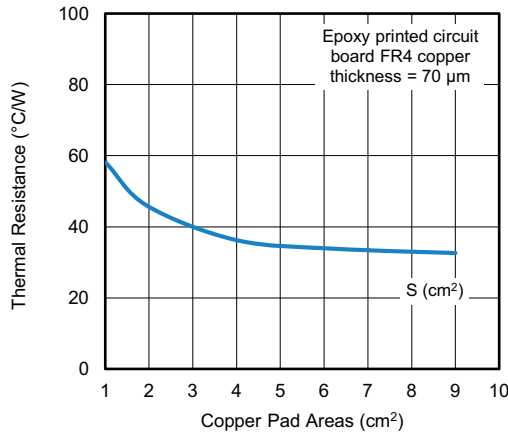
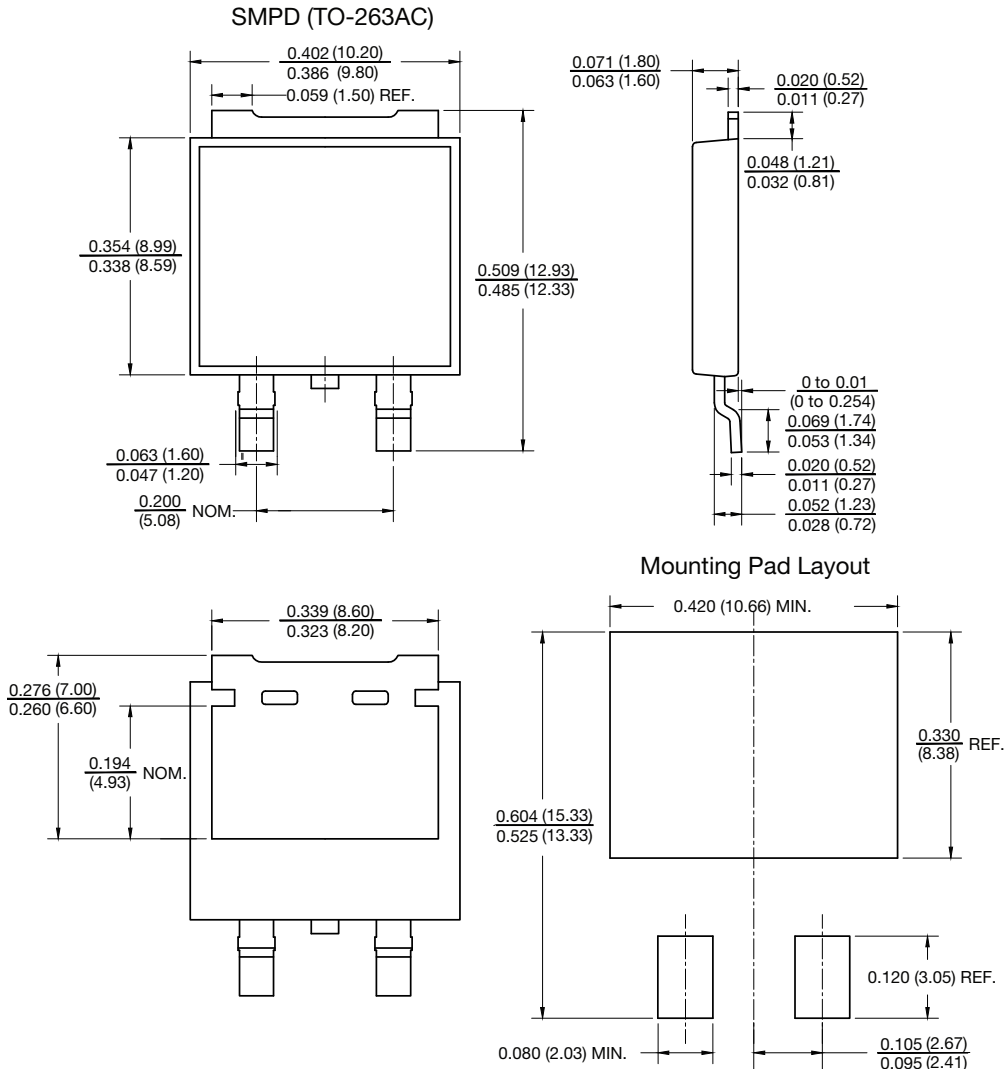


Fig. 7 - Thermal Resistance Junction-to-Ambient vs. Copper Pad Areas

**PACKAGE OUTLINE DIMENSIONS** in inches (millimeters)





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